

Product Features

- Multiple Output Frequencies (2, 3, or 4) Selectable
- QiK Chip[™] Technology
- Superior Jitter Performance (less than 0.25 ps RMS, 12 kHz - 20 MHz)
- SAW replacement better performance
- Frequencies from 50 MHz 1.4 GHz (LVDS/LVPECL/CML)
- Frequencies from 10 MHz 150 MHz (HCMOS)





Product Description

The multiple frequency oscillator utilizes MtronPTI's Qik Chip[™] technology to provide a very low jitter clock for all output frequencies. The M21x is available with up to 4 different frequency outputs from 10MHz through 1.4 GHz. The M21x utilizes the stable fundamental 3rd overtone crystal and the Qik Chip[™] IC to provide the wide range of output frequencies. Using this design approach, the M21x provides exceptional performance in frequency stability, jitter, phase noise and long term reliability.

Product Applications

- Global/Regional selection
- Forward Error Correction (FEC) / Selectable Functionality applications
- Telecommunications such as SONET / SDH / DWDM / FEC / SERDES / OC-3 thru OC-192
- 1-2-4-10 Gigabit Fibre Channel
- Wireless base stations / WLAN / Gigabit Ethernet

Product Ordering Information



xDSL, Network Communications

- Avionic flight controlsMilitary communications
- Clock and data recovery
- Low jitter clock generation
- Economy margining
- Frequency margining

Frequency Select Truth Table						
FS1 FS0						
Frequency 1	High	High				
Frequency 2	High	Low				
Frequency 3	Low	High				
Frequency 4 Low Low						

NOTE: Logic Low = 20% Vcc max. Logic High = 80% Vcc min.

*For three and four frequency selections, FS0=Pad A

M2120Sxxx, M2121Sxxx, M2122Sxxx, M2130Sxxx, M2131Sxxx, M2132Sxxx, M2140Sxxx, M2141Sxxx, M2142Sxxx - Contact factory for datasheets.



Performance Characteristics

	PARAMETER	Symbol	Min.	Тур.	Max.	Units	Condition/Notes			
	Frequency Range	F	50		1400	MHz	LVPECL/LVDS/CML - See Note 1			
			10 150				HCMOS			
	Operating Temperature	Та		-20 to +70)	°C	Quetemar Specified			
			-40 to +85				Customer Specified			
	Storage Temperature	Ts	-55 +125			°C				
	Frequency Stability	ΔF/F	See Ordering Information			ppm	See Note 2			
	Aging									
	1st Year		-3		+3	maa				
	Thereafter (per year)		-1		+1	ppm				
	Supply Voltage	Vcc	1.71	1.8	1.89	V				
	cappi, renage		2.375	2.5	2.625	v				
			3.135	3.3	3 465	v				
	Input Current	lcc	0.100	0.0	125	mA	I VPECI /HCMOS/CMI			
	input ourion				105	mA	LVDS			
	Load				100		See Note 3			
	2000		50 Ohms to (Vcc –2) Vdc				LVPECL Waveform			
							LVDS/CML Waveform			
					15	рF	CMOS Waveform			
su						p.	LDPECI : Vdd – 1.3 V			
tio	Symmetry (Duty Cycle)		45		55	%	LVDS: 1.25 V			
ica	Output Skew			20		ps	LVPECL			
ś				15		ps	CML			
al Spe				20		, ps	LVDS			
	Differential Voltage	Vod	250	350	450	mV	LVDS			
i	-	Vod	0.7	0.95	1.20	Vpp	CML			
Elect	Common Mode	Vcm		1.2		V	LVDS			
_	Logic "1" Level	Voh	Vcc -1.02			V	I VPECI			
		10	90% Vdd				HCMOS			
	Logic "0" Level	Vol	0070 100		Vcc -1 63	V	I VPECI			
	209.0 0 2010.	10.			10% Vdd	<u> </u>	HCMOS			
	Bise/Fall Time	Tr/Tf		0.23	0.35	ns	@ 20/80% LVPECL_LVDS_CMI			
					6.0	ns	Ref. 10%-90% Vdd HCMOS			
	Enable Function		80% Vcc m	in. or N/C:	Output active					
	Option B		0.5V max: C	Dutput disa	bles to high-Z	Customer Specified				
	Enable Function		0.5V max or	r N/C: Outp	out active	Questa en Que e lífica d				
	Option S		80% Vcc m	in: Output o	disables to hig	Customer Specified				
	Tristate Function		Input Logic	"1" or floati	ing: output acti	Quatemar Creatified				
			Input Logic	"0": output	disables to hid	gh-Z	Customer Specified			
	Frequency Selection		See Truth T	able	Let a let					
	Settling Time				10	ms	To within ± 1 ppm of frequency			
	Start up Time				10	ms				
	Phase Jitter									
	@ 622.08 MHz	φJ		0.25		ps RMS	LVPECL/LVDS/CML			
							Integrated 12 kHz – 20 MHz			
	@ 125 MHz				0.50	ps RMS	HCMOS (12 kHz – 20 MHz)			
ntal	Mechanical Shock	Per MIL-S	D-202, Metho	d 213, Cor	ndition C (100	g's, 6 mS du	ration, 1/2 sinewave)			
nei	Vibration	Per MIL-S	ID-202, Metho	d 201 & 20	04 (10 g's from	10-2000 Hz)			
0U	Hermeticity	Per MIL-S	D-202, Metho	od 112, (1x	10° atm. cc/s	ot Helium)				
۲	Thermal Cycle	Per MIL-S	FD-883, Metho	od 1010, Co	ondition B (-55	°C to +125°C	c, 15 min. dwell, 10 cycles)			
ш	Solderability	Per EIAJ-S	STD-002							
	Max. Soldering Cond.	See solder profile, Figure 1								

Note 1: Contact factory for standard frequency availability over 945 MHz.

Note 2: Stability is inclusive of initial tolerance, deviation over temperature, shock, vibration, supply voltage, and aging for one year at 50°C mean ambient temperature.

Note 3: See Load Circuit Diagram in this datasheet. Consult factory with nonstandard output load requirements.



Phase Noise Plot



Output Waveform







Product Dimension & Pinout Information



PAD 1 ENABLE

Pad1: Enable/Disable or Tristate Pad2: N/C or FS0 Pad3: Ground Pad4: Output Q (LVPECL,LVDS,CML,HCMOS) Pad5: Output Q (LVPECL,LVDS,CML) N/C for HCMOS Pad6: Vcc PadA: FS0 or N/C PadB: FS1 PadC: Do not connect!

PAD 2 ENABLE

Pad1: N/C or FS0 Pad2: Enable/Disable or Tristate Pad3: Ground Pad4: Output Q (LVPECL,LVDS,CML,HCMOS) Pad5: Output Q (LVPECL,LVDS,CML) N/C for HCMOS Pad6: Vcc PadA: FS0 or N/C PadB: FS1 PadC: Do not connect!



Handling Information

Although protection circuitry has been designed into the M21x oscillator, proper precautions should be taken to avoid exposure to electrostatic discharge (ESD) during handling and mounting. MtronPTI utilizes a human-body model (HBM) and a charged-device model (CDM) for ESD-susceptibility testing and protection design evaluation. ESD voltage thresholds are dependent on the circuit parameters used to define the mode. Although no industry-wide standard has been adopted for the CDM, a standard HBM (resistance = 1500 Ω , capacitance = 100 pF) is widely used and therefore can be used for comparison purposes. The HBM ESD threshold presented here was obtained using these circuit parameters.

Model	ESD Threshold, Minimum	Unit	
Human Body	1500*	V	
Charged Device	1500*	V	

* MIL-STD-833D, Method 3015, Class 1



Quality Parameters

Environmental Specifications/Qualification Testing Performed on the M21x Clock Oscillator							
Test	Test Method	Test Condition					
Electrical Characteristics	Internal Specification	Per Specification					
Frequency vs. Temperature	Internal Specification	Per Specification					
Mechanical Shock	MIL-STD-202, Method 213, C	100 g's					
Vibration	MIL-STD-202, Method 201-204	10 g's from 10-2000 Hz					
Thermal Cycle	MIL-STD-883, Method 1010, B	-55 Deg. C to +125 Deg. C, 15 minute Dwell, 10 cycles					
Aging	Internal Specification	168 Hours at 105 Degrees C					
Gross Leak	MIL-STD-202, Method 112	30 Second Immersion					
Fine Leak	MIL-STD-202, Method 112	Must meet 1x10 ⁻⁸					
Solderability	MIL-STD-883, Method 2003	8 Hour Steam Age – Must Exhibit 95% coverage					
Resistance to Solvents	MIL-STD-883, Method 2015	Three 1 minute soaks					
Terminal Pull	MIL-STD-883, Method 2004, A	2 Pounds					
Lead Bend	MIL-STD-883, Method 2004, B1	1 Bending Cycle					
Physical Dimensions	MIL-STD-883, Method 2016	Per Specification					
Internal Visual	Internal Specification	Per Internal Specification					

Part Marking Guide

Line 1: Model Number

- Line 2: Frequency
- Line 3: Date Code
- Line 4: Pin 1 Indicator / MtronPTI





Tape & Reel Specifications

(all measurements are in mm)	Α	В	С	D	E	F	G	н	I	J	к	L
M21x	6.51	9.29	1.5	7.5	2.8	4	8/12	16	180-330	13	21	60-100



Standard Tape and Reel: 1000 parts per reel



Maximum Soldering Conditions

Solder Conditions

Note: Exceeding these limits may damage the device.



Typical Test Circuit & Load Circuit Diagrams



Product Revision Table

Date	Revision	PCN Number	Details of Revision
7/20/07	А	10118	IC Revision to improve phase noise and electrical performance

For custom products or additional specifications contact our sales team at 800.762.8800 (toll free) or 605.665.9321

For more information on this product visit the MtronPTI website at www.mtronpti.com